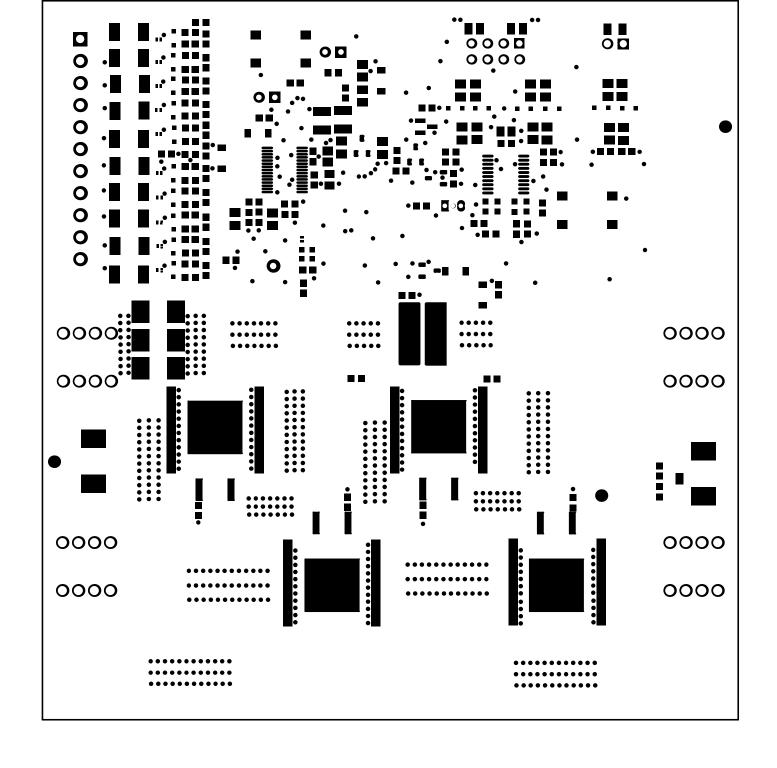
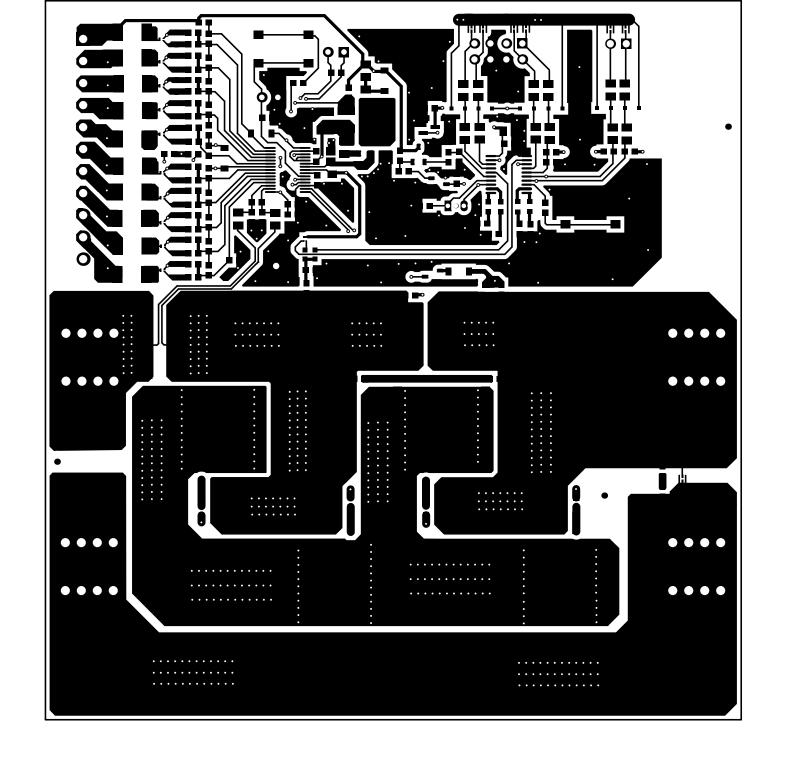


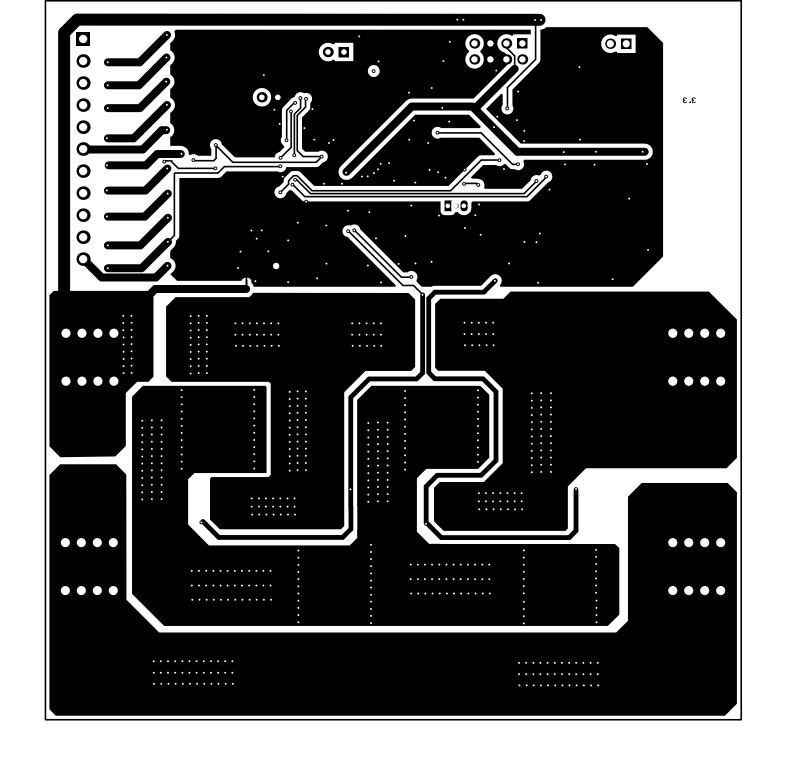
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00449	REV: 3.3	SUN REU:	Not In VersionControl
LAYER NAME = Top Overlay				
PLOT NAME = Top Overlay	GENERATED : 9/24/2	2015 11:53:58	AM	TEXAS INSTRUMENTS



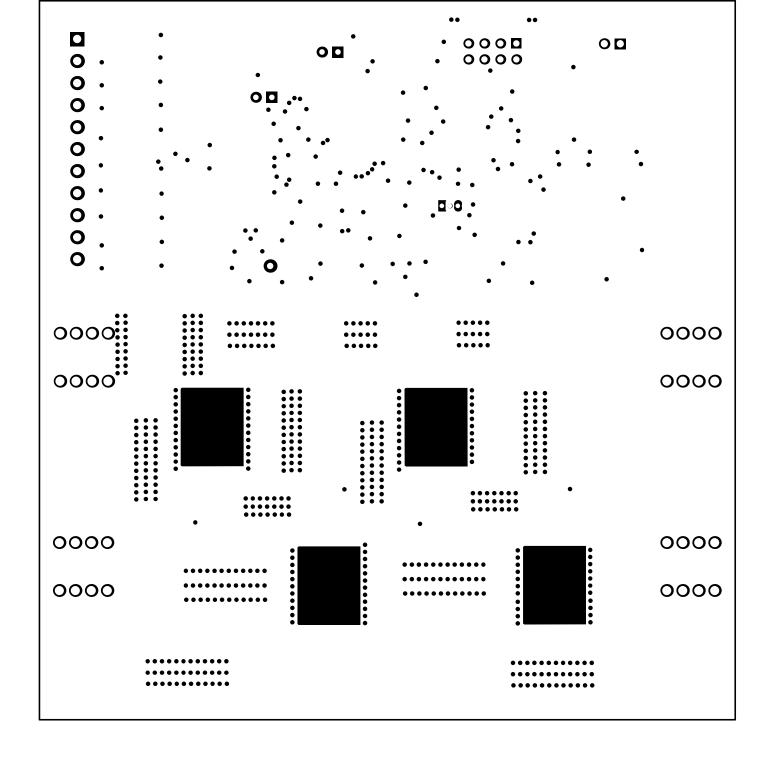
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00449	REV: 3.3	SUN REV:	Not In VersionControl
LAYER NAME = Top Solder				
PLOT NAME = Top Solder Mask	GENERATED : 9/24/2	2015 11:54:01	AM	TEXAS INSTRUMENTS



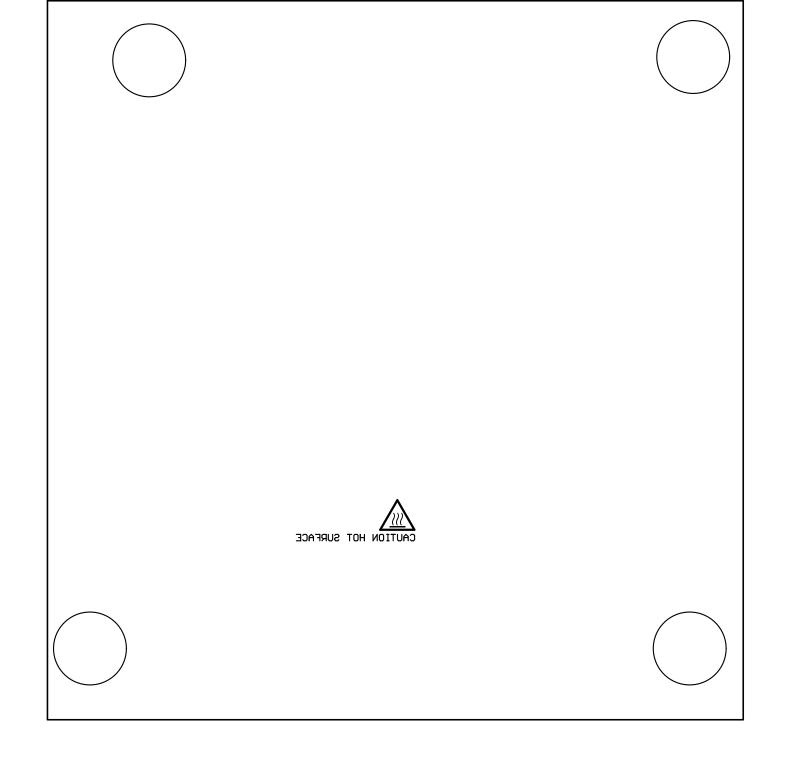
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00449	REV: 3.3	SUN REU:	Not In VersionControl
LAYER NAME = Top Layer				
PLOT NAME = Top Layer	GENERATED : 9/24/2	2015 11:54:03	AM	TEXAS INSTRUMENTS



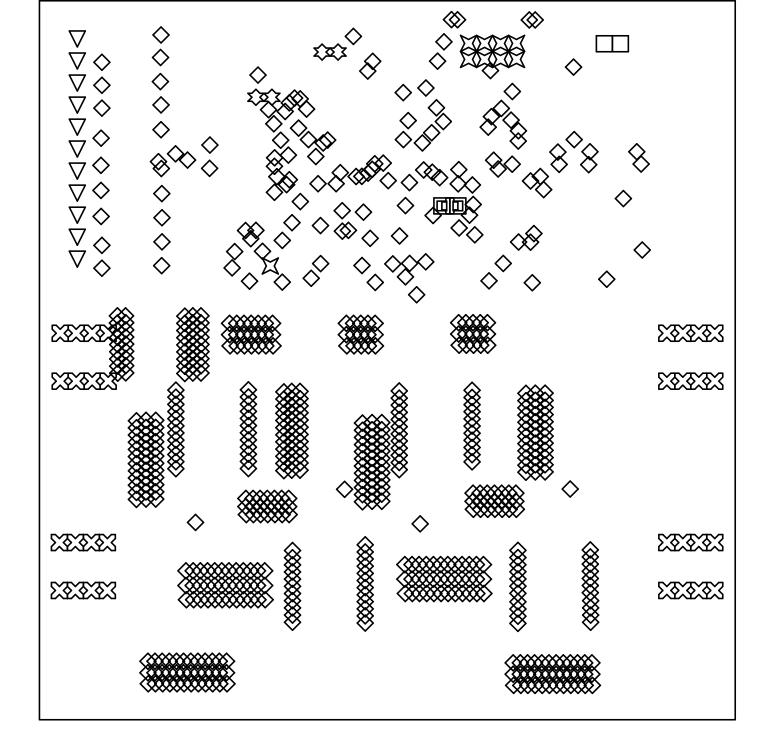
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00449	REV: 3.3	SUN REU	: Not In VersionControl
LAYER NAME = Bottom Layer				
PLOT NAME = Bottom Layer	GENERATED : 9/24/2	2015 11:54:05	AM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00449	REV: 3.3	SUN REU: Not In VersionControl	
LAYER NAME = Bottom Solder				
PLOT NAME = Bottom Solder Mask	GENERATED : 9/24/2	2015 11:54:08	8 AM TEXAS INSTRUMENTS	

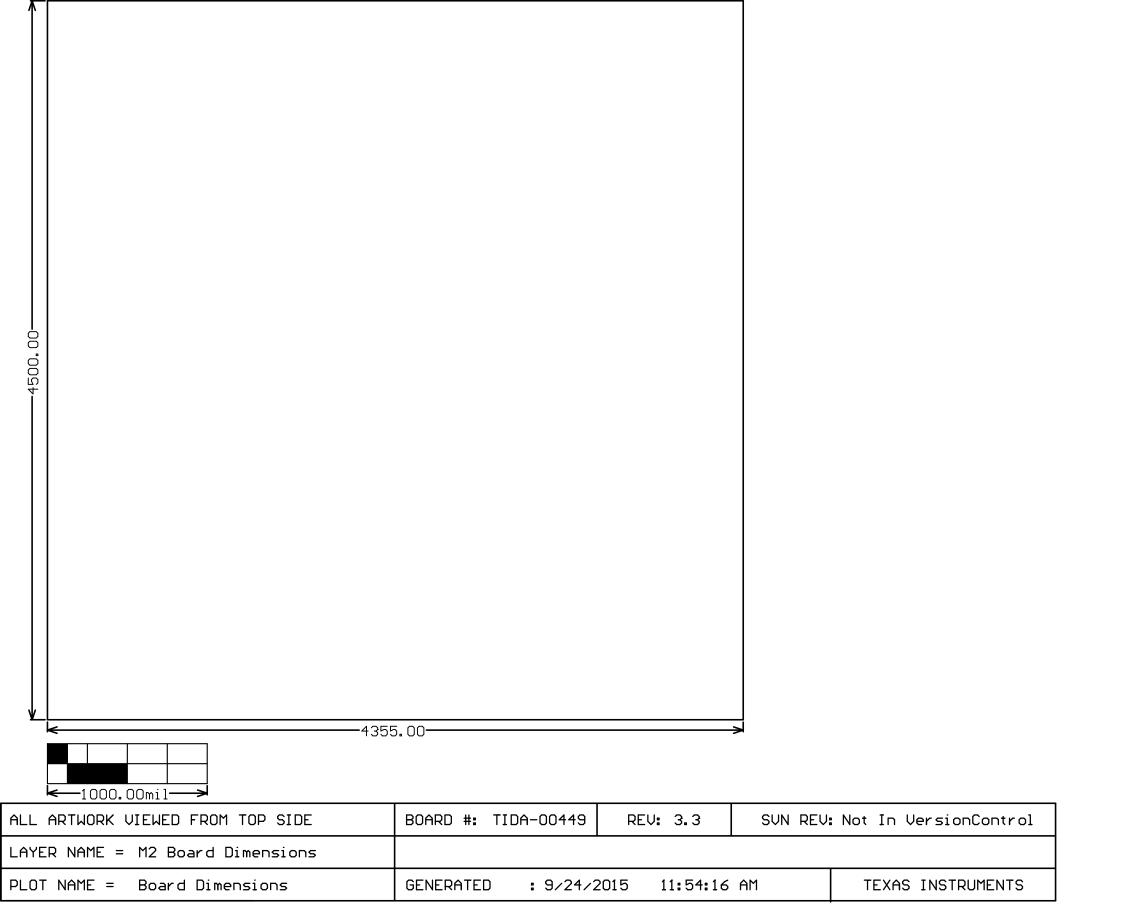


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00449	REV: 3.3	SUN REV:	Not In VersionControl
LAYER NAME = Bottom Overlay				
PLOT NAME = Bottom Overlay	GENERATED : 9/24/2	2015 11:54:11	AM	TEXAS INSTRUMENTS



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
O	1	29.53mil (0.750mm)	NPTH	Round
♦	665	12.00mil (0.305mm)	PTH	Round
	2	29.53mil (0.750mm)	PTH	Round
\$	4	35.00mil (0.889mm)	РТН	Round
Ħ	9	40.00mil (1.016mm)	PTH	Round
	2	45.28mil (1.150mm)	РТН	Round
∇	11	52.00mil (1.321mm)	PTH	Round
×	32	57.09mil (1.450mm)	РТН	Round
	726 Total			
×		57.09mil (1.450mm)	РТН	Round

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00449	REV: 3.3	SUN REV:	Not In VersionControl
LAYER NAME = Drill Drawing				
PLOT NAME = Drill Drawing	GENERATED : 9/24/2	2015 11:54:13	AM	TEXAS INSTRUMENTS



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